

Bill of Materials

Ref/Part name	pcs/unit	Description	Manufacturer	Value	Part Number	MPN	PCB Package	Rtd Voltage	Min Oper Temp	Max Oper Temp
C2	1	CAPACITOR, CERAMIC X5R, 2.2uF, 10V, - 20%/+20%, -55DEGC/+85DEGC, 0603, SMD	MURATA	2.2uF	02-01132	GRM188R61A225ME34D	0603	10V	-55DEGC	+85DEGC
C3	1	CAPACITORS, CERAMIC, 1uF, 15%, X5R, 10V, 0603, SMD	MURATA	1uF	02-01389	GRM188R61A105KA61D	0603	10V	-55DEGC	+85DEGC
C4	0	CAPACITOR, DO NOT MOUNT, 0603, SMD		DNM	02-01324					
C21 C31	2	CAPACITOR, CERAMIC COG/NPO, 47pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	MURATA	47pF	02-04366	GRM1555C1H470JA01D	0402	50V	-55DEGC	+125DEGC
C41	1	CAPACITOR, CERAMIC X5R, 4.7uF, 6.3V, - 10%/+10%, -55DEGC/+85DEGC, 0603, SMD	MURATA	4.7uF	02-02418	GRM188R60J475KE19D	0603	6.3V	-55DEGC	+85DEGC
C101 C151 C241 C331 C361 C391 C431	7	CAPACITOR, CERAMIC X7R, 100nF, 6.3V, - 10%/+10%, -55DEGC/+125DEGC, 0402, SMD	MURATA	100nF	02-02323	GRM155R70J104KA01D	0402	6.3V	-55DEGC	+125DEGC
C281	1	CAPACITOR, CERAMIC X7R, 1nF, 50V, - 10%/+10%, -55DEGC/+125DEGC, 0402, SMD	MURATA	1nF	02-02070	GRM155R71H102KA01D	0402	50V	-55DEGC	+125DEGC
C321 C551 C561	3	CAPACITOR, CERAMIC X5R, 1uF, 10V, - 10%/+10%, -55DEGC/+85DEGC, 0402, SMD	MURATA	1uF	02-02381	GRM155R61A105KE15D	0402	10V	-55DEGC	+85DEGC
C341 C351	2	CAPACITOR, CERAMIC COG/NPO, 12pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	MURATA	12pF	02-04168	GRM1555C1H120JA01D	0402	50V	-55DEGC	+125DEGC
C371 C381	2	CAPACITOR, CERAMIC COG/NPO, 18pF, 50V, - 55DEGC/+125DEGC, 0402, SMD	MURATA	18pF	02-02407	GRM1555C1H180JA01D	0402	50V	-55DEGC	+125DEGC
C372 C382	2	CAPACITOR, CERAMIC COG/NPO, 1pF, 50V, - 0.1pF/+0.1pF, -55DEGC/+125DEGC, 0402, SMD	MURATA	1pF	02-04367	GRM1555C1H1R0BA01D	0402	50V	-55DEGC	+125DEGC
C373	1	CAPACITOR, CERAMIC COG/NPO, 1.2pF, 50V, 0.25pF/+0.25pF, -55DEGC/+125DEGC, 0402, SMD	MURATA	1.2pF	02-04524	GRM1555C1H1R2CA01D	0402	50V	-55DEGC	+125DEGC
C374	0	CAPACITOR, DO NOT MOUNT, 0402, SMD		DNM	02-01321					
C392	1	CAPACITOR, CERAMIC COG/NPO, 220pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	MURATA	220pF	02-01276	GRM1555C1H221JA01D	0402	50V	-55DEGC	+125DEGC
C441 C451	2	CAPACITOR, CERAMIC COG/NPO, 22pF, 50V, -5%/+5%, -55DEGC/+125DEGC, 0402, SMD	MURATA	22pF	02-04373	GRM1555C1H220JA01D	0402	50V	-55DEGC	+125DEGC
FL1	1	FILTER, EMI, 1500@100MHz, - 55DEGC/+125DEGC, 0603, SMD	MURATA	BLM18HE152SN 1	04-00470	BLM18HE152SN1D	0603		-55DEGC	+125DEGC
11	1	CONNECTOR, USB-B, 5 PINS, PITCH 0.65mm, SMD	Тусо	1981568-1	06-02244	1981568-1			N/A	N/A
J2	0	CONNECTOR, COAX RF, DO NOT MOUNT								
L372 L373 L381	3	INDUCTOR, CHIP, 2nH, -0.3nH/ +0.3nH, 0.3A, -55DEGC/+125DEGC, 0402, SMD	MURATA	2nH	03-06525	LQG15HS2N0S02D	0402		-55DEGC	+125DEGC
L374	0	INDUCTOR, DO NOT MOUNT, 0402, SMD		TBD	03-01022					



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								, and the second		
1 1	1	INDUCTOR, STANDARD, 3.3nH, -	MURATA	3.3nH	03-06501	LQG15HS3N3S02D	0402		-55DEGC	+125DEGC
		0.3nH/+0.3nH, 0.3A, -55DEGC/+125DEGC,								
		0402, SMD								
P1 P2 2	2	CONNECTOR, HEADER, FEMALE, STRAIGHT,	SAMTEC	SFM-110-02-S-D-	06-02251	SFM-110-02-SM-D-A-K-TR			-55DEGC	+125DEGC
		2 ROWS, 20 PINS, PITCH 1.27mm, SMD		A-K-TR						
23	0	CONNECTOR, DO NOT MOUNT, SMD								
P5 1	1	CONNECTOR, HEADER, STRAIGHT, MALE, 4	GradConn Cable	BB02-HP041-	06-02190	BB02-HP041-KB3-060B00			-40DEGC	+105DEGC
		PINS, 2 ROWS, 2.54mm PITCH, SMD		KB3-060B00						
P6	0	CONNECTOR, DO NOT MOUNT	AMP TYCO	826629-2	06-00059	826629-2		750V	-65DEGC	+105DEGC
			ELECTRONICS							
R1 R442 R452	0	RESISTOR, DO NOT MOUNT, 0402, SMD		DNM	01-02475					
R21 R31	2	RESISTOR, THICK FILM, 33, -1%/+1%,	KOA SPEER	33	01-16853	RK73H1ETTP33R0F	0402	50V	-55DEGC	+155DEGC
		0.063W, 50V, -55DEGC/+155DEGC, 0402, SMD								
R32 1	1	RESISTOR, THICK FILM, 1.5k, -1%/+1%,	KOA SPEER	1.5k	01-16854	RK73H1ETTP1501F	0402	50V	-55DEGC	+155DEGC
		0.063W, 50V, -55DEGC/+155DEGC, 0402,								
		SMD								
R41 1	1	RESISTOR, THICK FILM, 2, -1%/+1%, 0.063W,	KOA SPEER	2	01-16855	RK73H1ETTP2R00F	0402	50V	-55DEGC	+155DEGC
		50V, -55DEGC/+155DEGC, 0402, SMD								
R281	1	RESISTOR, THICK FILM, 2.2k, -1%/+1%,	KOA SPEER	2.2k	01-11503	RK73H1ETTP2201F	0402	50V	-55DEGC	+155DEGC
		0.063W, 50V, -55DEGC/+155DEGC, 0402,								
		SMD								
R421	1	RESISTOR, THICK FILM, 56k, -1%/+1%,	KOA SPEER	56k	01-16848	RK73H1ETTP5602F	0402	50V	-55DEGC	+155DEGC
		0.063W, 50V, -55DEGC/+155DEGC, 0402,								
		SMD								
R441 R451	2	RESISTOR, JUMPER, -55DEGC/+155DEGC,	KOA SPEER	0	01-01784	RK73Z1ETTP	0402		-55DEGC	+155DEGC
		0402, SMD								
U1	1	IC, ANALOG, ARM CORTEX M3 MCU WITH	TEXAS INSTRUMENTS	CC2538F512RKU	18-27810	CC2538F512RKU	VQFN56	2V TO 3.6V	-40DEGC	+125DEGC
		2.4GHz IEEE 802.15.4 ZigBee, 2V TO 3.6V, -								
		40DEGC/+125 DEGC, VQFN56, SMD								
U2	1	IC, ANALOG, ULTRALOW-POWER LINEAR	TEXAS INSTRUMENTS	TPS76933	18-00550	TPS76933DBVT	SOT23-5	3.3V	-40DEGC	+125DEGC
		REGULATORS, VIN:32.7V TO 10V, VOUT:							1.000	
		3.3V, SOT23-5, SMD								
X1	1	CRYSTAL, OSCILATOR, 32MHz, 10pF, -	Epson Toyocom	32MHz	12-00422	FA-128 32MHz 10pF 10PPM	SMD		-40DEGC	+85DEGC
	Ī	10PPM/+10PPM, -40DEGC/+85DEGC, SMD	Epson Toyocom	52	12 00 .22	77, 120 522 10p. 10	5.11.5		100200	1035200
		, 10.1, 102200, 1032200, 31115								
(2	1	CRYSTAL, OSCILATOR, 32.768kHz, -20PPM/+	Epson Toyocom	32.768kHz	12-00430	FC-12M 32.768kHz 20ppm			-40DEGC	+85DEGC
^2	[20PPM, -40DEGC/ +85DEGC, 12.5pF, SMD	p							
Total number of	47									
components to be										

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